



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Chiba, T., et al.
Appl. No.: 09/576,681
Filed: May 23, 2000
Title: SHAPE OF MICRODOT MARK FORMED BY LASER BEAM AND
MICRODOT MARKING METHOD
Art Unit: 1725
Examiner: L. Edmondson
Docket No.: 112780-4

Commissioner for Patents
Washington, DC 20231

RECEIVED
MAR 08 2002
TC 1700

RESPONSE TO OFFICE ACTION

Sir:

This Response is submitted in response to the Office Action dated October 11, 2001. Applicants respectfully submit that the Application is in condition for allowance. However, Applicants invite the Examiner to call Applicants' representative to discuss any issues with the Application.

REMARKS

The Office Action was issued on pending claims 1-10. In this Response, no Claims have been amended, added or cancelled. Thus, Claims 1-10 are pending in the case.

In Office Action paragraph 1, Claims 1 and 7-10 were rejected under 37 U.S.C. § 102(b) as being anticipated by Ota et al., U.S. Patent No. 5,477,309. Applicants respectfully disagree.

Regarding Claim 1, the invention pertains to a microdot mark shape which is formed by a laser beam on a surface of an article to be marked by using a laser as a light source. The microdot mark shape is made by dot marks each formed on each laser irradiated point. The mark has a protrusion which protrudes in the center portion upward from the surface of the article to be marked. Also, the length of each dot mark along the surface of the article to be marked is 1.0 to 15.0 μm .

Ota et al. is directed to an alignment apparatus which purportedly serves to accurately position a wafer with respect to a wafer processing apparatus. More particularly, Ota et al. pertains to an alignment apparatus which irradiates detection laser beams LB1, LB2 on an alignment mark to detect a position of a wafer 1. See Fig. 1 of Ota et al. The alignment mark or